

Solder paste NP303-DPS101-T5

Product description

GENMA SMD solder paste – our dispenser solder paste NP303-DPS101-T5 was developed to meet the high requirements during laser-soldering and it also makes for excellent results with reflow soldering. The solder paste does not splatter and creates no tin beads or flux spatter beside the soldering joint. It produces attractive soldering joints that are surrounded by clear flux residues. The solder paste features a consistent adhesiveness during the pick-and-place process. Its consistent viscosity provides for an even and reproducible dispenser application. Cleaning after soldering is not necessary. The solder paste can be soldered under air or nitrogen reflow.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11
Powder size (µm)	10 - 25, type 5	IPC-TM-650-2.2.14.2
Viscosity (Pa · s)	130	IPC-TM-650-2.4.34.3
Flux content (wt %)	12.3	IPC-TM-650-2.3.34.1
Flux type	ROL0, no clean	IPC-J-STD-004B
Halide content (wt %)	< 0,03	IPC-TM-650-2.3.35
Insulation resistance (Ω)	$\geq 5.9 \times 10^{12}$ (40°C 90 % r. L)	IPC-TM-650-2.6.3.3
Insulation resistance (Ω)	$\geq 4.3 \times 10^9$ (85°C 85 % r. L)	IPC-TM-650-2.6.3.3
Migration test	No migration	IPC-TM-650-2.6.14.1
Copper mirror test	No corrosion	IPC-TM-650-2.3.32
Packaging	cartridge (80g)	
Shelf life	3 month at 0-10°C	
Transport	keep cool	
Tempering the solder paste	Set to room temperature before opening to avoid condensation.	
Recommended temperature during dispensing (°C)	25 ± 3	
Recommended relative humidity in % during dispensing	50 ± 20	

Compliance

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 26.02.2024)